

# SOT617-24

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

18 November 2019

Package information

## 1 Package summary

<b>Terminal position code</b>	Q (quad)
<b>Package type descriptive code</b>	HVQFN32
<b>Package type industry code</b>	HVQFN32
<b>Package style descriptive code</b>	HVQFN (thermal enhanced very thin quad flatpack; no leads)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	30-10-2019
<b>Manufacturer package code</b>	98ASA01550D

Table 1. Package summary

Parameter	Min	Nom	Max	Unit
package length	4.9	5	5.1	mm
package width	4.9	5	5.1	mm
package height	0.8	0.85	0.9	mm
nominal pitch	-	0.5	-	mm
actual quantity of termination	-	32	-	



HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

2 Package outline

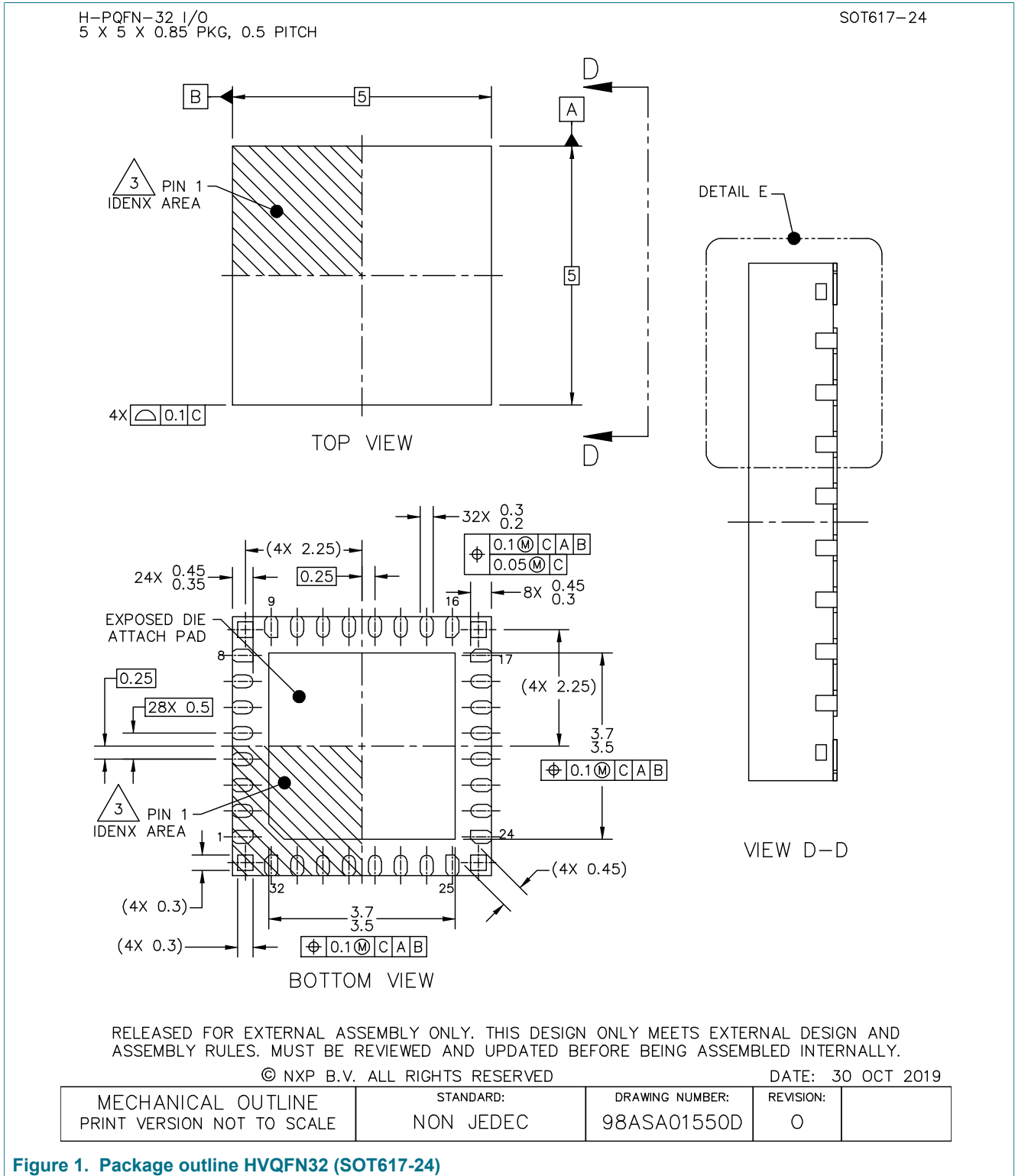
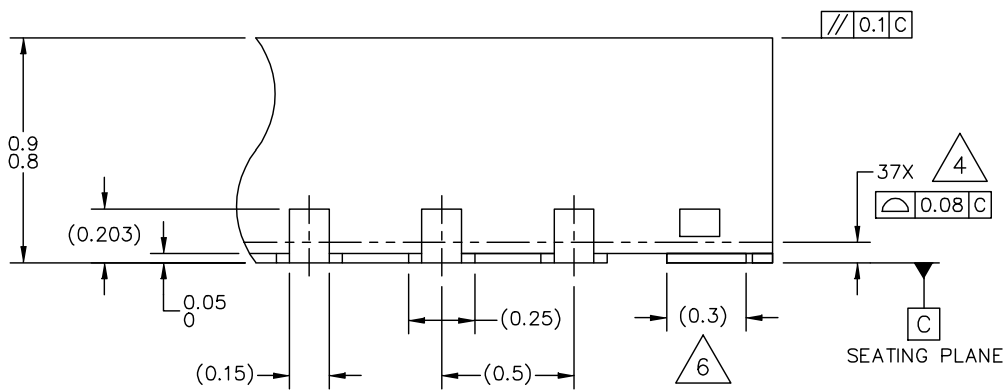


Figure 1. Package outline HVQFN32 (SOT617-24)

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

H-PQFN-32 I/O  
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-24



DETAIL E  
VIEW ROTATED 90° CW

RELEASED FOR EXTERNAL ASSEMBLY ONLY. THIS DESIGN ONLY MEETS EXTERNAL DESIGN AND ASSEMBLY RULES. MUST BE REVIEWED AND UPDATED BEFORE BEING ASSEMBLED INTERNALLY.

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DATE: 30 OCT 2019

MECHANICAL OUTLINE PRINT VERSION NOT TO SCALE	STANDARD: NON JEDEC	DRAWING NUMBER: 98ASA01550D	REVISION: 0	
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Figure 2. Package outline detail E of HVQFN32 (SOT617-24)

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

3 Soldering

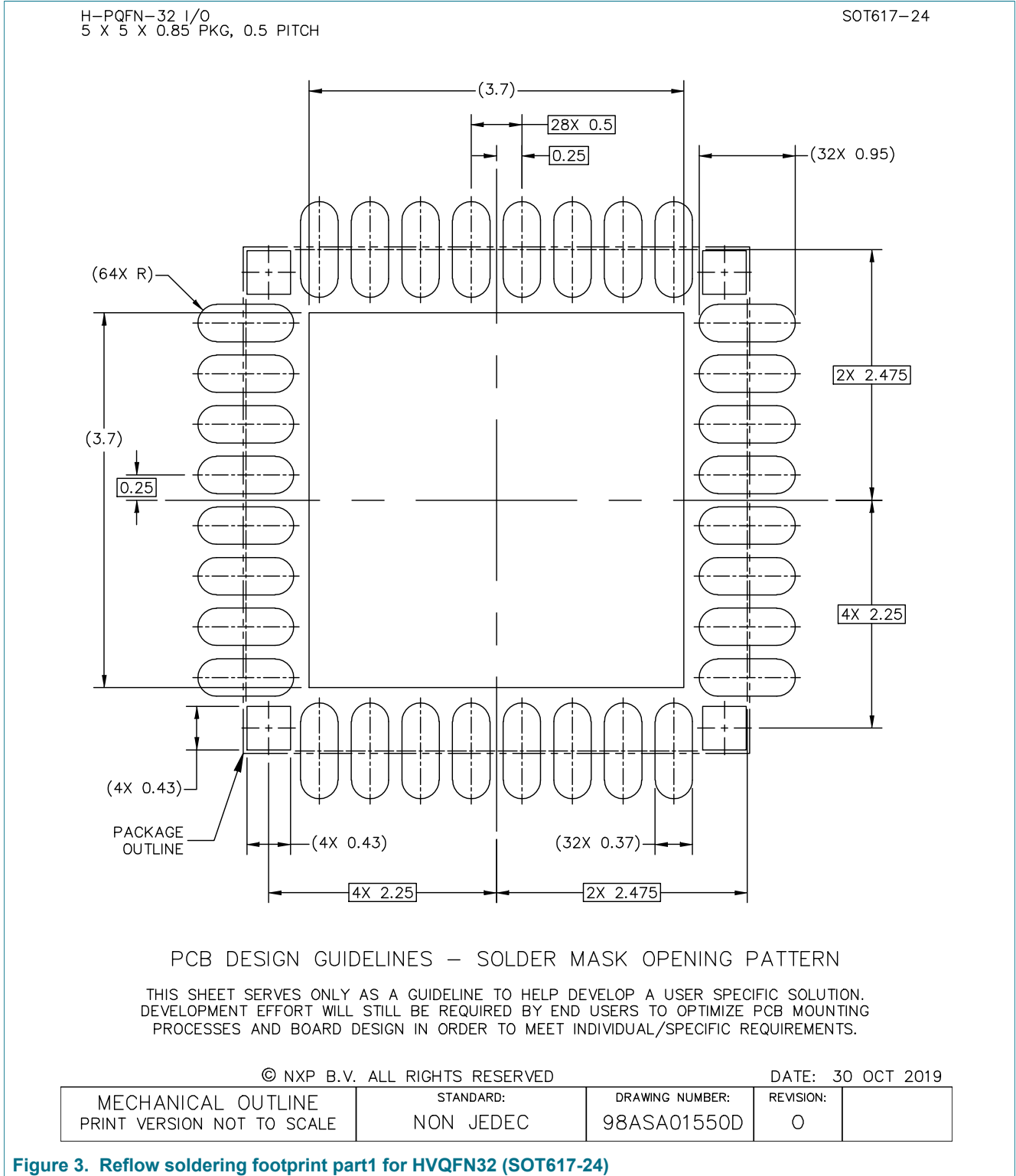


Figure 3. Reflow soldering footprint part1 for HVQFN32 (SOT617-24)

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

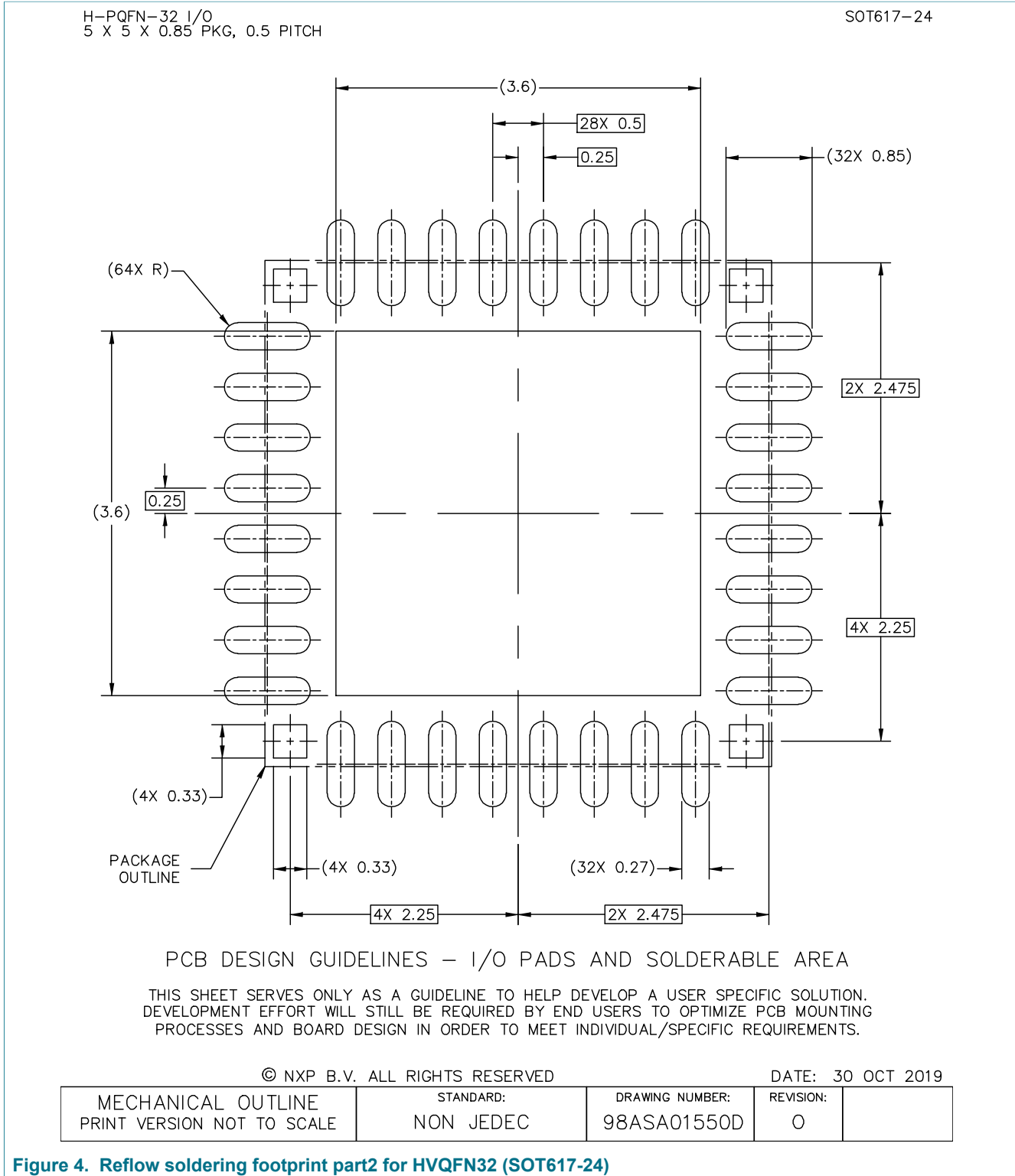


Figure 4. Reflow soldering footprint part2 for HVQFN32 (SOT617-24)

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

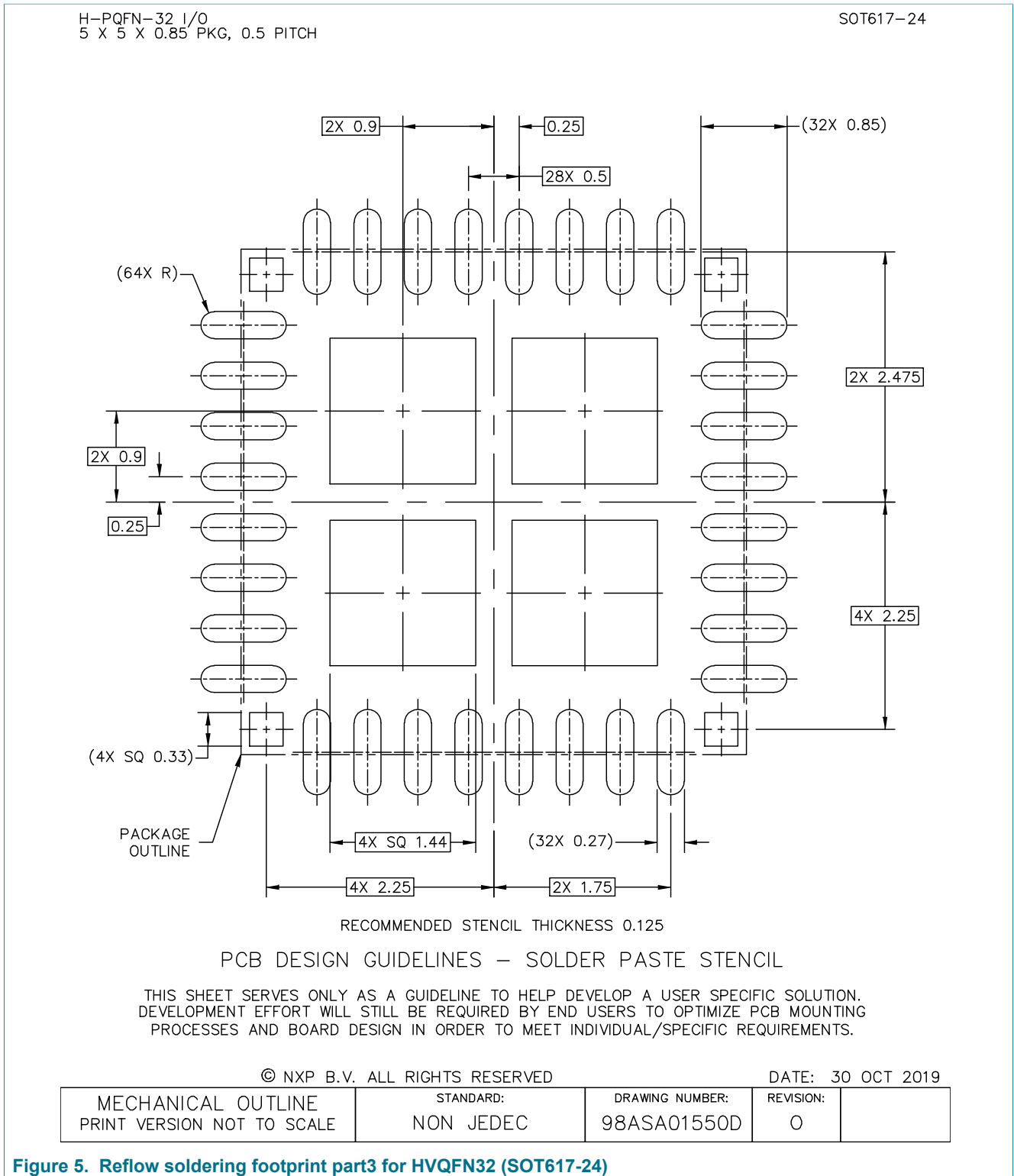


Figure 5. Reflow soldering footprint part3 for HVQFN32 (SOT617-24)

HVQFN32, plastic, thermal enhanced very thin quad flat package, no leads; 32 terminals; 0.5 mm pitch; 5 mm x 5 mm x 0.85 mm body

H-PQFN-32 I/O  
5 X 5 X 0.85 PKG, 0.5 PITCH

SOT617-24

NOTES:

1. ALL DIMENSIONS ARE IN MILLIMETERS.
2. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994.
3. PIN 1 FEATURE SHAPE, SIZE AND LOCATION MAY VARY.
4. COPLANARITY APPLIES TO LEADS, DIE ATTACH FLAG AND CORNER NON-FUNCTIONAL PADS.
5. MIN. METAL GAP SHOULD BE 0.15 MM.
6. ANCHORING PADS.

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Figure 6. Package outline note of HVQFN32 (SOT617-24)

## 4 Legal information

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